

**POSITION ACCURACY INSPECTING METHOD,
POSITION ACCURACY INSPECTING APPARATUS, AND POSITION INSPECTING UNIT**

ABSTRACT

A contact position of a probe needle with respect to electrode pads 71 to 75 of a semiconductor device is inspected in advance when performing an inspection by a prober on the semiconductor device formed on a wafer W placed on a stage 11. A reticle 31 on which shapes 61 to 65 indicating positions of the probe needles are formed is placed instead of the probe needles at a position where the probe needles are arranged. The semiconductor device formed on the wafer W is imaged by the imaging unit 33 through the reticle 31. A positional relationship between the shapes formed on the reticle 31 and the electrode pads 71 to 75 is analyzed from the image. When necessary, a position of the stage 11 is adjusted such that centers of the shapes 61 to 65 and centers of the electrode pad 71 to 75 are coincident.

Figure 3B